

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1-10 (cancelled)

Claim 11 (currently amended): A method for removing adhesive coatings from a plurality of substrates having dense submicron topography containing prominent sidewalls, comprising the steps of:

~~placing a quartz gas distribution plate, connected to a pressure regulated gas~~

~~supply, in a tank containing a liquid chemical;~~

~~submerging and placing a substrate carrier, containing a plurality of substrates, on~~

~~said quartz gas distribution plate so that said substrates are aligned and in a~~

~~vertical position relative to said quartz gas distribution plate;~~

~~said quartz distribution plate directs gas bubbles between and parallel to each~~

~~surface of said substrates aligned thereabove, said gas distribution plate~~

~~providing a chemical mechanical scrubbing;~~

~~removing said substrate carrier from said chemical liquid.~~

providing a substrate carrier containing a plurality of substrates;

providing a tank containing a liquid chemical;

placing a quartz gas distribution plate on bottom of said tank, said quartz gas

distribution plate having trough means for guiding a flexible tubing and drill
guide means for drilling a linear array of holes in said guided flexible tubing,
said flexible tubing connected to a pressure regulated gas supply;
positioning said substrate carrier on said quartz gas distribution plate so that a
linear array of gas bubbles flowing upwards scrub surfaces between each
substrate.

Claim 12 (currently amended): The method according to claim 11 wherein trough
and drill guide means ~~quartz gas distribution plate having~~ providing ~~distribution means~~
~~for generating an array~~ a plurality of linear of gas bubbles, ~~each row of said array patterns~~
that correspond[[ing]] to each [[a]] substrate ~~position of said~~ contained in said substrate
carrier.

Claim 13 (original): The method according to claim 11 wherein said pressure
regulated gas supply is nitrogen gas.

Claim 14. (currently amended): The method according to claim 11 wherein ~~using~~ a
quartz gas distribution plate with a flexible tubing are each [[is]] compatible with
aggressive chemicals used for removing adhesive residues in metal sidewalls that are
coated with polymer.

Claim 15. (currently amended) A method for stripping adhesive photoresist from a

plurality of semiconductor wafers having dense submicron topography containing prominent sidewalls, comprising the steps of:

providing a wafer cassette containing a plurality of wafers;

providing a tank containing a photoresist stripping chemical;

providing a quartz gas distribution plate and placing it on bottom of said tank, said

quartz gas distribution plate having trough means for guiding a flexible tubing

and drill guide means for drilling a linear array of holes in said guided flexible

tubing, said flexible tubing connected to a pressure regulated gas supply;

positioning said wafer cassette on said quartz gas distribution plate so that a

linear array of gas bubbles emanating from holes drilled in said flexible tubing,

flow upwards, therein scrubbing the surfaces of each wafer.

~~horizontally placing a quartz gas distribution plate, connected to a pressure~~

~~regulated nitrogen supply, in an open tank containing a photoresist stripping chemical;~~

~~submerging and placing a wafer cassette containing a plurality of wafers on said~~

~~quartz gas distribution plate so that said wafers are aligned and in a vertical position relative to said quartz gas distribution plate;~~

~~said distribution plate directs nitrogen bubbles between and parallel to each~~

~~surface of said wafers aligned thereabove, said nitrogen bubbles providing a chemical-mechanical scrubbing;~~

~~removing said wafer cassette from said photoresist stripping liquid.~~

Claim 16. (currently amended): The method according to claim 15 wherein said quartz gas distribution plate having a gas distribution pattern means for generating ~~[[an]]~~ rows ~~array~~ of nitrogen bubbles, each row ~~of said array~~ corresponding to a wafer position ~~contained~~ in said wafer cassette.

Claim 18. (currently amended): The method according to claim 15 wherein using a quartz gas distribution plate and flexible tubing that are ~~[[is]]~~ compatible with aggressive chemicals for removing adhesive residues in metal sidewalls ~~that are~~ coated with adhesive photoresist.

Claim 19. (new): The method according to claim 15 wherein said pressure regulated gas supply is nitrogen gas.